

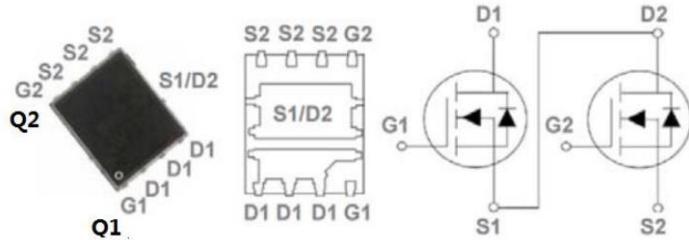
Features

- Low $R_{DS(on)}$ @ $V_{GS}=10V$
- 100% UIS Tested
- Pb-Free, RoHS Compliant

$V_{(BR)DSS}$	$R_{DS(ON)} \text{ Typ}$	$I_D \text{ Max}$
40V	10mΩ @10V	30A
	18mΩ @4.5V	

Applications

- Load Switch
- *Switching Circuits*
- *High Speed line Driver*
- *Power management*


TDFN3X3
Order Information

Product	Package	Marking	Packing
SIZ320DT-T1-GE3-CN	TDFN3X3	4466	3000PCS/Reel

Absolute Maximum Ratings

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Symbol	Parameter	Rating	Unit
Common Ratings (TA=25°C Unless Otherwise Noted)			
V_{GS}	Gate-Source Voltage	±20	V
$V_{(BR)DSS}$	Drain-Source Breakdown Voltage	40	V
T_J	Maximum Junction Temperature	150	°C
T_{STG}	Storage Temperature Range	-50 to 150	°C
Mounted on Large Heat Sink			
I_{DM}	Pulse Drain Current Tested①	$T_A=25^\circ\text{C}$	A
I_D	Continuous Drain Current	$T_A=25^\circ\text{C}$	30
		$T_A=70^\circ\text{C}$	24
P_D	Maximum Power Dissipation	$T_A=25^\circ\text{C}$	26
EAS	Avalanche energy, single pulsed ②	29	W
R_{JAC}	Thermal Resistance Junction-Ambient	4.8	

Symbol	Parameter	Condition	Min	Typ	Max	Unit
Static Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
$V_{(\text{BR})\text{DSS}}$	Drain-Source Breakdown Voltage	$V_{\text{GS}}=0\text{V}$, $I_D=250\mu\text{A}$	40	-	-	V
I_{DSS}	Zero Gate Voltage Drain Current($T_A=25^\circ\text{C}$)	$V_{\text{DS}}=40\text{V}$, $V_{\text{GS}}=0\text{V}$	-	-	1	μA
	Zero Gate Voltage Drain Current($T_A=125^\circ\text{C}$)	$V_{\text{DS}}=32\text{V}$, $V_{\text{GS}}=0\text{V}$	-	-	100	nA
I_{GSS}	Gate-Body Leakage Current	$V_{\text{GS}}=\pm 20\text{V}$, $V_{\text{DS}}=0\text{V}$	-	-	± 100	nA
$V_{\text{GS}(\text{TH})}$	Gate Threshold Voltage	$V_{\text{DS}}=V_{\text{GS}}$, $I_D=250\mu\text{A}$	1.2	1.6	2.5	V
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=10$, $I_D=4\text{A}$	-	10	13	$\text{m}\Omega$
$R_{\text{DS}(\text{ON})}$	Drain-Source On-State Resistance②	$V_{\text{GS}}=4.5\text{V}$, $I_D=3\text{A}$	-	18	22	$\text{m}\Omega$
Dynamic Electrical Characteristics @ $T_J = 25^\circ\text{C}$ (unless otherwise stated)						
C_{iss}	Input Capacitance	$V_{\text{DS}}=20\text{V}$, $V_{\text{GS}}=0\text{V}$, $f=1\text{MHz}$	-	407	-	pF
C_{oss}	Output Capacitance		-	195	-	pF
C_{rss}	Reverse Transfer Capacitance		-	7.7	-	pF
Q_g	Total Gate Charge	$V_{\text{DS}}=20\text{V}$, $I_D=15\text{A}$, $V_{\text{GS}}=10\text{V}$	-	6.9	-	nC
Q_{gs}	Gate Source Charge		-	1.3	-	nC
Q_{gd}	Gate Drain Charge		-	3.0	-	nC
Switching Characteristics						
$t_{\text{d}(\text{on})}$	Turn on Delay Time	$V_{\text{DD}}=20\text{V}$, $I_D=1\text{A}$, $R_G=3.3\Omega$, $V_{\text{GS}}=10\text{V}$	-	17.2	-	ns
t_r	Turn on Rise Time		-	29.6	-	ns
$t_{\text{d}(\text{off})}$	Turn Off Delay Time		-	46.8	-	ns
t_f	Turn Off Fall Time		-	34.6	-	ns
Source Drain Diode Characteristics						
I_{SD}	Source drain current(Body Diode)	$T_A=25^\circ\text{C}$	-	-	2	A
V_{SD}	Forward on voltage②	$T_J=25^\circ\text{C}$, $I_{\text{SD}}=4\text{A}$, $V_{\text{GS}}=0\text{V}$	-	0.84	1.2	V

Notes:

① Pulse width limited by maximum allowable junction temperature

② Pulse test ; Pulse width $\leq 300\mu\text{s}$, duty cycle $\leq 2\%$.

Typical Characteristics

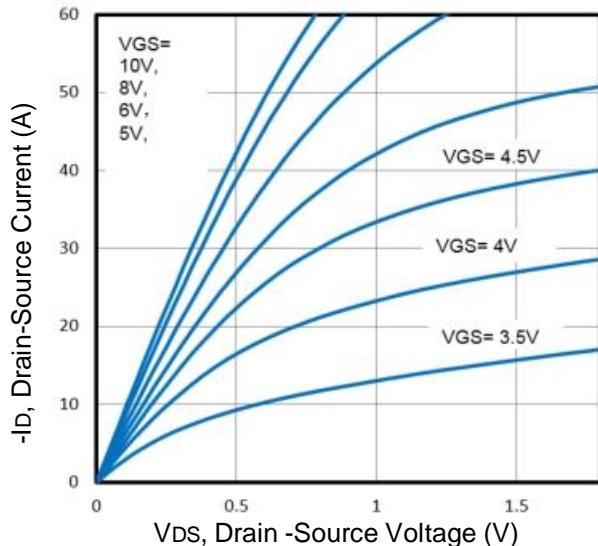


Fig1. Typical Output Characteristics

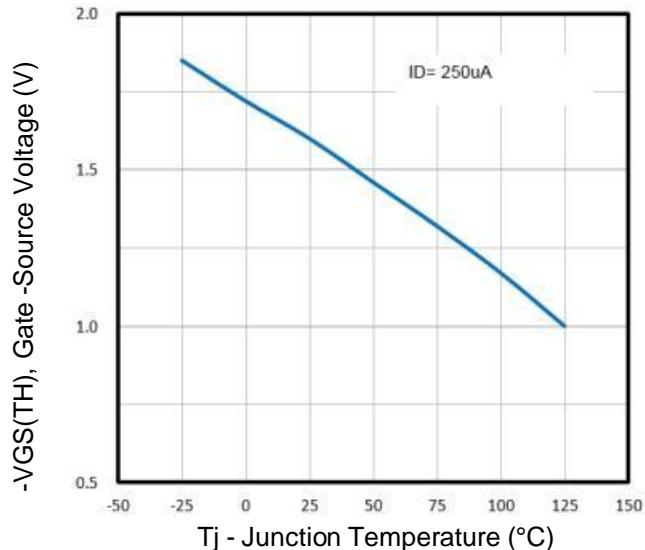


Fig2. Normalized Threshold Voltage Vs. Temperature

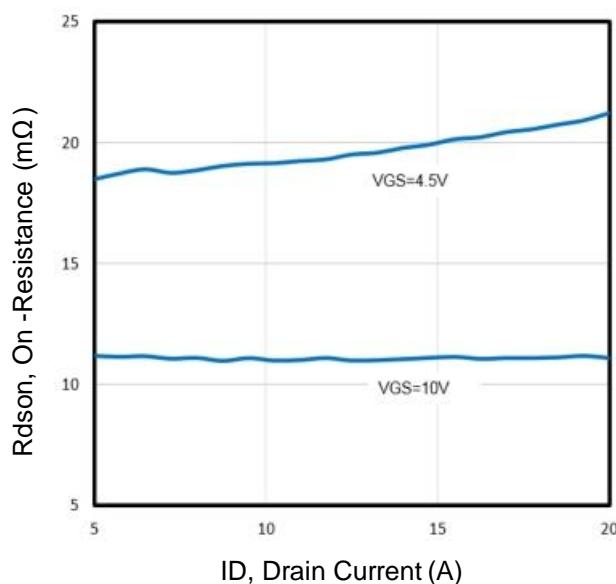


Fig3. On-Resistance vs. Drain Current and Gate

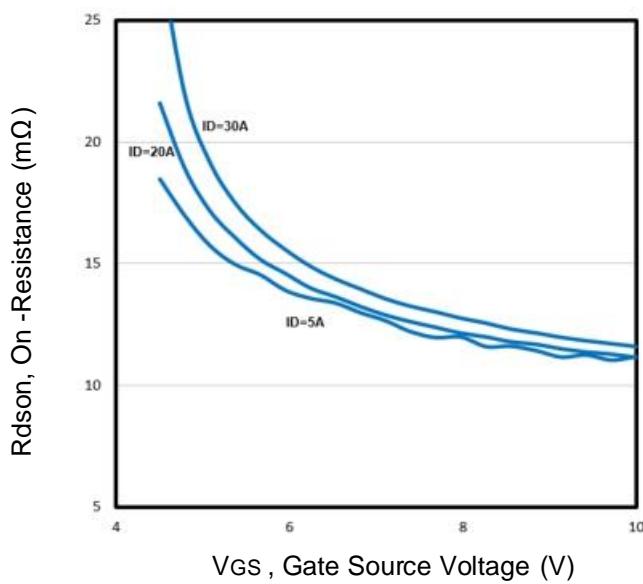


Fig4. On-Resistance vs. Gate Source Voltage

Typical Characteristics

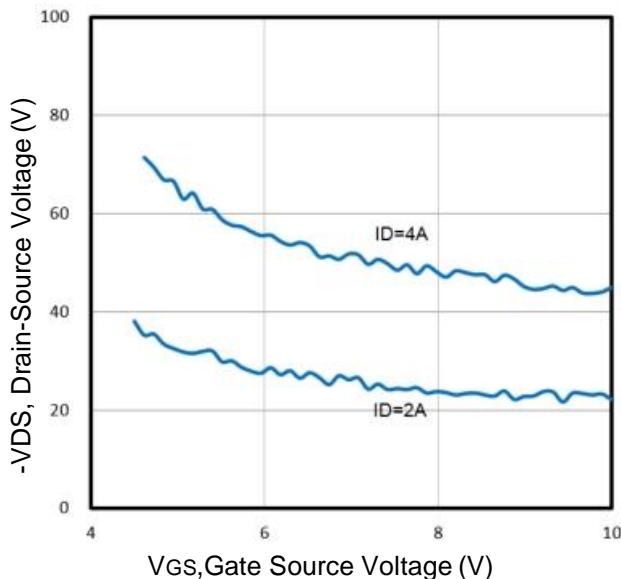


Fig5. Drain-Source Voltage vs Gate-Source Voltage

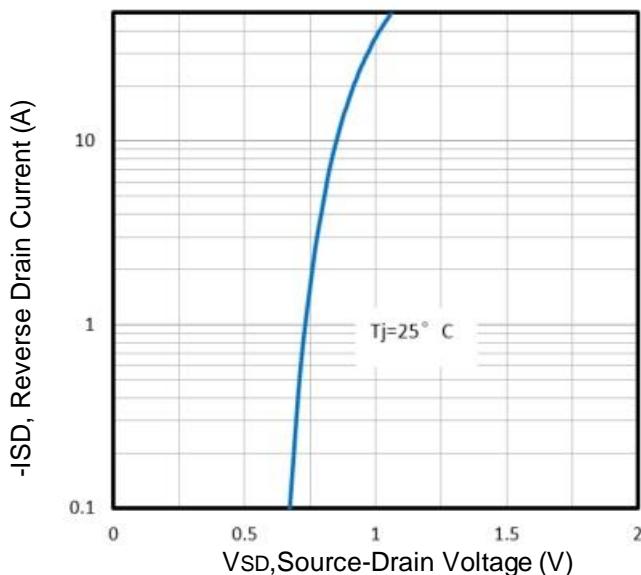


Fig6. Typical Source-Drain Diode Forward Voltage

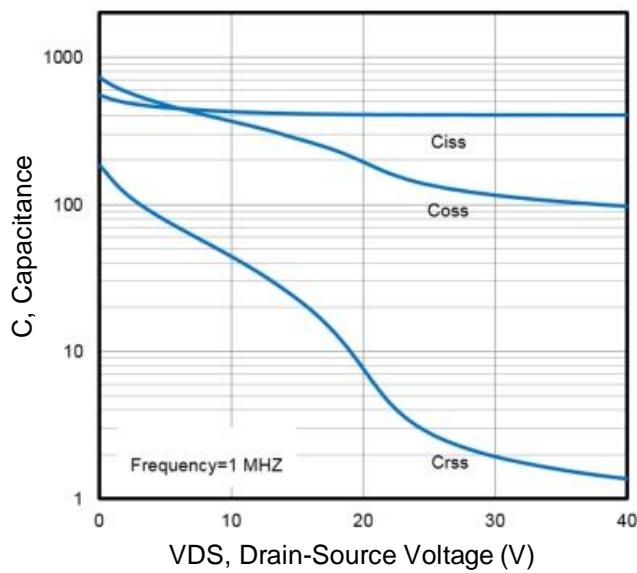


Fig7. Typical Capacitance Vs. Drain-Source Voltage

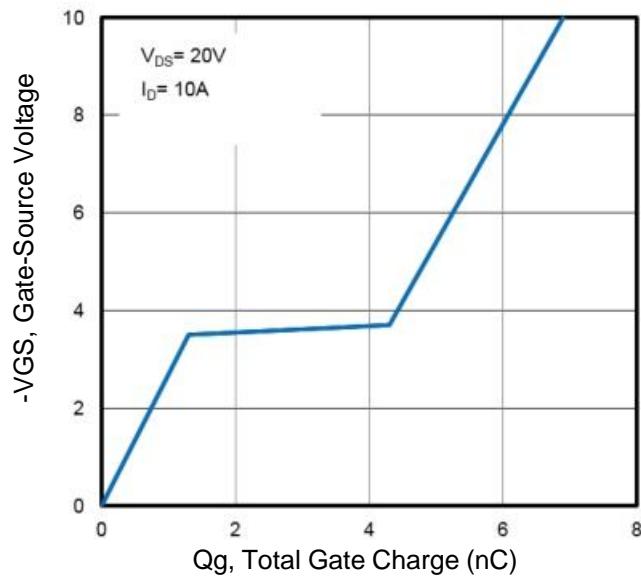
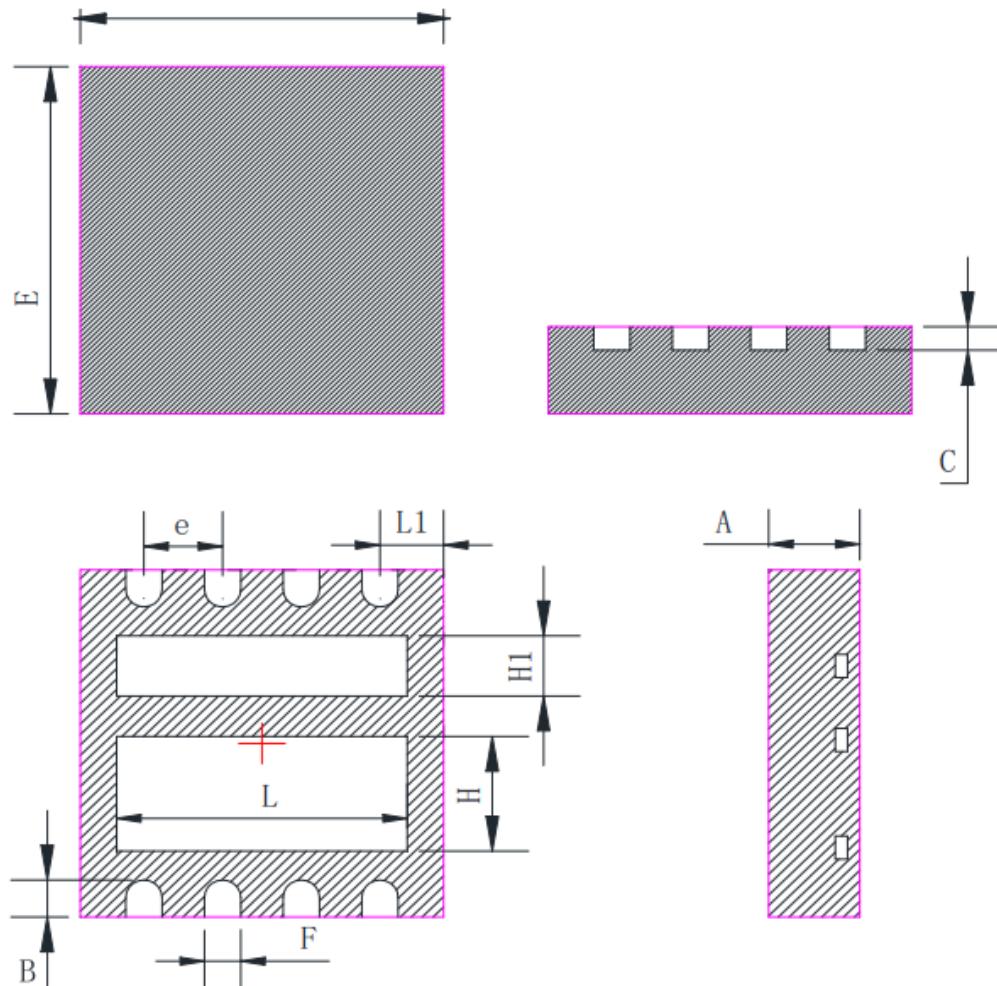


Fig8. Typical Gate Charge Vs. Gate-Source Voltage

TDFN3X3 Mechanical Data


Symbol	Min	Typ	Max
A	0.70	0.75	0.80
B	0.27	0.32	0.37
C	0.153	0.203	0.253
D	2.90	3.00	3.10
E	2.90	3.00	3.10
e	0.60	0.65	0.70
F	0.25	0.30	0.35
H	0.89	0.99	1.09
H1	0.42	0.52	0.62
L	2.30	2.40	2.50
L1	0.425	0.525	0.625



ChipNobo Co., Ltd

SIZ320DT-T1-GE3-CN

**40V/30A Dual N Channel
Advanced Power MOSFET**

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